

4

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D

C

B

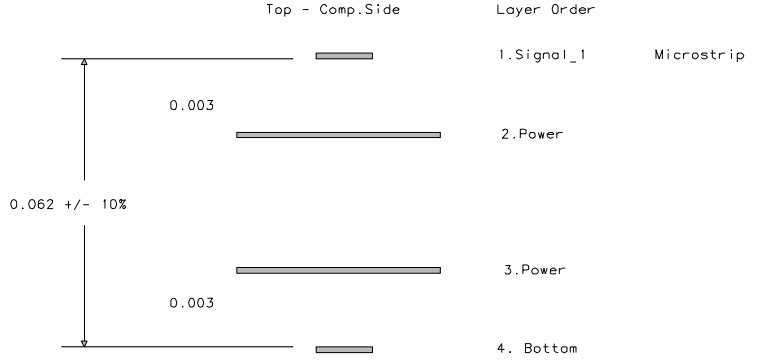
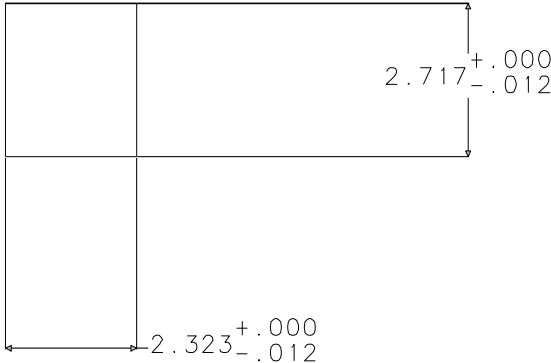
A

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A



Board Characteristics - 4 LAYER BOARD

- 0. All dimensions are given in inches unless specified otherwise.
- 1. Material FR4 , Tg > 170 C.
- 2. General minimum trace width and clearance: 4 mils
There is a special area on the board, top side with clearance: 2.5 mils.
The size of this special area is 0.3' by 0.3'
- 3. Impedance control: 50 Ohm for all 4 mil signal traces, top and bottom.
- 4. 1/2 oz copper for signal layers (top and bottom).
1 oz copper for power and ground planes.
- 5. Immersion Gold over copper, with min. Ni: 2.5-5 um; Au: 0.05-0.2 um.
- 6. Apply Solder Mask over bare copper.
- 8. Silkscreen on Component and Solder Sides.
- 11. Interlayer spacing as specified

BOARD'S DRILL SCHEDULE

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Tolerance	COMMENT
○	.008	287	YES	---	
⊞	.013	10	YES	---	
⊕	.032	20	YES	---	
⊞	.041	10	YES	---	
⊖	.094	1	NO	---	
⊞	.106	4	NO	---	

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES .XXX .XX DO NOT SCALE DRAWING			CONTRACT NO.		UNIVERSITY OF CHICAGO ELECTRONICS DEVELOPMENT GROUP		
			APPROVALS	DATE	TITLE		
TREATMENT	DRAWN	M. Bogdan	3/11/2011	PSEC3 - Flip Mezzanine Specification Drawing			
FINISH	CHECKED	M. Bogdan	3/11/2011	SIZE	FSCM NO.	DWG. NO.	REV.
SIMILAR TO	ACT. WT	CALC. WT	ISSUED			2729	A
				SCALE	1/2	SHEET	

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